

Title (en)

APPARATUS FOR THERMAL TREATMENT OF THIN FILM WAFER

Title (de)

THERMISCHE BEHANDLUNGSVORRICHTUNG FÜR DÜNNE FILM-HALBLEITERBLÄTTCHEN

Title (fr)

APPAREIL DE TRAITEMENT THERMIQUE DE TRANCHES A COUCHE MINCE

Publication

EP 0702775 A1 19960327 (EN)

Application

EP 95911781 A 19950215

Priority

- KR 19940002820 A 19940217
- US 9502008 W 19950215

Abstract (en)

[origin: WO9523427A2] The apparatus of the present invention is for the thermal treatment of a thin film wafer and includes a vacuum chamber, a heater block, a holding clamp for receiving the heater block and for holding a wafer and which includes a specific weight to press the wafer against the heater block, a wafer supply means for supplying the wafer to, positioning the wafer on and removing the wafer from the holding clamp, and an elevator means for moving the holding clamp toward and away from the heater block to permit thermal treatment of the wafer in the vacuum chamber. The present invention advantageously supplies and removes the wafer together with minimizing damage to the wafer due to excess clamping force.

IPC 1-7

F26B 13/30; **C23C 16/00**; **B05C 13/00**; **B05C 13/02**; **B05C 21/00**

IPC 8 full level

C30B 25/12 (2006.01); **C30B 31/14** (2006.01); **C30B 35/00** (2006.01); **H01L 21/00** (2006.01)

CPC (source: EP KR)

C30B 25/12 (2013.01 - EP); **C30B 31/14** (2013.01 - EP); **C30B 35/005** (2013.01 - EP); **H01L 21/67115** (2013.01 - EP); **H01L 21/68** (2013.01 - KR)

Designated contracting state (EPC)

CH DE GB LI NL

DOCDB simple family (publication)

WO 9523427 A2 19950831; **WO 9523427 A3 19951228**; EP 0702775 A1 19960327; EP 0702775 A4 19960731; KR 950025850 A 19950918

DOCDB simple family (application)

US 9502008 W 19950215; EP 95911781 A 19950215; KR 19940002820 A 19940217